

April 2015

# **NDT2955**

# P-Channel Enhancement Mode Field Effect Transistor

## **General Description**

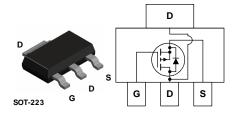
This 60V P-Channel MOSFET is produced using Fairchild Semiconductor's high voltage Trench process. It has been optimized for power management plications.

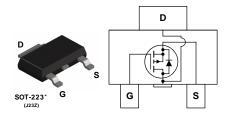
# **Applications**

- DC/DC converter
- Power management

# **Features**

- -2.5 A, -60 V.  $R_{DS(ON)}=300m\Omega$  @  $V_{GS}=-10$  V  $R_{DS(ON)}=500m\Omega$  @  $V_{GS}=-4.5$  V
- High density cell design for extremely low R<sub>DS(ON)</sub>
- High power and current handling capability in a widely used surface mount package.





Absolute Maximum Ratings T<sub>A</sub>=25°C unless otherwise noted

	<u> </u>			
Symbol	Parameter		Ratings	Units
V <sub>DSS</sub>	Drain-Source Voltage		-60	V
V <sub>GSS</sub>	Gate-Source Voltage		±20	V
I <sub>D</sub>	Drain Current - Continuous	(Note 1a)	-2.5	Α
	– Pulsed		<b>–15</b>	
P <sub>D</sub>	Maximum Power Dissipation	(Note 1a)	3.0	W
		(Note 1b)	1.3	
		(Note 1c)	1.1	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range		-55 to +150	°C

# **Thermal Characteristics**

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	42	°C/W
R <sub>e,JC</sub>	Thermal Resistance, Junction-to-Case	(Note 1)	12	

**Package Marking and Ordering Information** 

Device Marking Device		Reel Size	Tape width	Quantity
2955	NDT2955	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Avalanc	he Ratings	1		ı		
W <sub>DSS</sub>	Drain-Source Avalanche Energy	Single Pulse, $V_{DD} = 30 \text{ V}$ , $I_D = 2.5 \text{ A}$			174	mJ
Off Char	acteristics					
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = -250 \mu\text{A}$	-60			V
<u>ΔBV<sub>DSS</sub></u> ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	$I_D$ = -250 $\mu$ A, Referenced to 25°C		-60		mV/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = -60 \text{ V},  V_{GS} = 0 \text{ V}$			-10	μΑ
GSSF	Gate-Body Leakage, Forward	$V_{GS} = -20 \text{ V},  V_{DS} = 0 \text{ V}$			100	nA
$I_{GSSR}$	Gate-Body Leakage, Reverse	$V_{GS} = -20 \text{ V},  V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = -250 \mu A$	-2	-2.6	-4	V
$\Delta V_{GS(th)} \ \Delta T_J$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \mu A$ , Referenced to 25°C		5.7		mV/°C
R <sub>DS(on)</sub>	Static Drain-Source	$V_{GS} = -10 \text{ V},  I_{D} = -2.5 \text{ A}$		95	300	$m\Omega$
	On–Resistance	$V_{GS} = -4.5 \text{ V},  I_D = -2 \text{ A}$		163 153	500 513	
I <sub>D(on)</sub>	On–State Drain Current	$V_{GS}$ =-10 V, $I_D$ =-2.5 A, $T_J$ =125°C $V_{GS}$ = -10 V, $V_{DS}$ = -5 V	-12	133	313	Α
9 <sub>FS</sub>	Forward Transconductance	$V_{DS} = -10 \text{ V},  I_{D} = -2.5 \text{ A}$	12	5.5		S
	Characteristics	155 10 1, 15 110 11			l	
C <sub>iss</sub>	Input Capacitance	$V_{DS} = -30 \text{ V},  V_{GS} = 0 \text{ V},$		601		pF
Coss	Output Capacitance	f = 1.0 MHz		85		pF
C <sub>rss</sub>	Reverse Transfer Capacitance	7		35		pF
Switchin	ng Characteristics (Note 2)	1	1	ı	ı	
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = -30 \text{ V},  I_{D} = -1 \text{ A},$		12	21	ns
t <sub>r</sub>	Turn-On Rise Time	$V_{GS} = -10 \text{ V},  R_{GEN} = 6 \Omega$		10	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time			19	34	ns
t <sub>f</sub>	Turn-Off Fall Time			6	12	ns
$Q_g$	Total Gate Charge	$V_{DS} = -30 \text{ V},  I_{D} = -2.5 \text{ A},$		11	15	nC
$Q_{gs}$	Gate-Source Charge	V <sub>GS</sub> = -10 V		2.4		nC
$Q_{gd}$	Gate-Drain Charge			2.7		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
l <sub>s</sub>	Maximum Continuous Drain-Source				-2.5	Α
V <sub>SD</sub>	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V},  I_{S} = -2.5 \text{ A}  \text{(Note 2)}$		-0.8	-1.2	V
t <sub>rr</sub>	Diode Reverse Recovery Time	$I_F = -2.5 \text{ A},$		25		nS
Q <sub>rr</sub>	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$		40		nC

### Notes

1.  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta CA}$  is determined by the user's board design.



a) 42°C/W when mounted on a 1in² pad of 2 oz copper



b) 95°C/W when mounted on a .0066 in² pad of 2 oz



c) 110°C/W when mounted on a minimum pad.

**<sup>2.</sup>** Pulse Test: Pulse Width <  $300\mu$ s, Duty Cycle < 2.0%

# **Typical Characteristics**

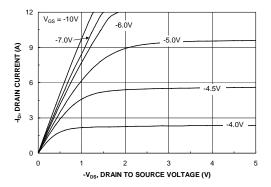


Figure 1. On-Region Characteristics.

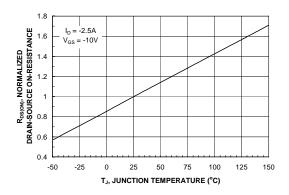


Figure 3. On-Resistance Variation withTemperature.

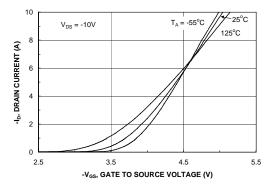


Figure 5. Transfer Characteristics.

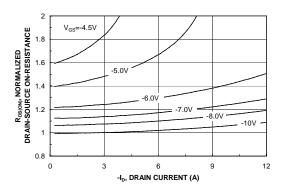


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

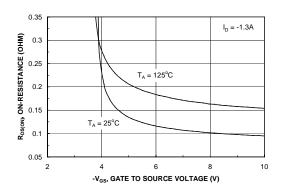


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

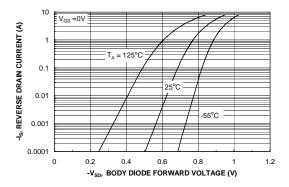
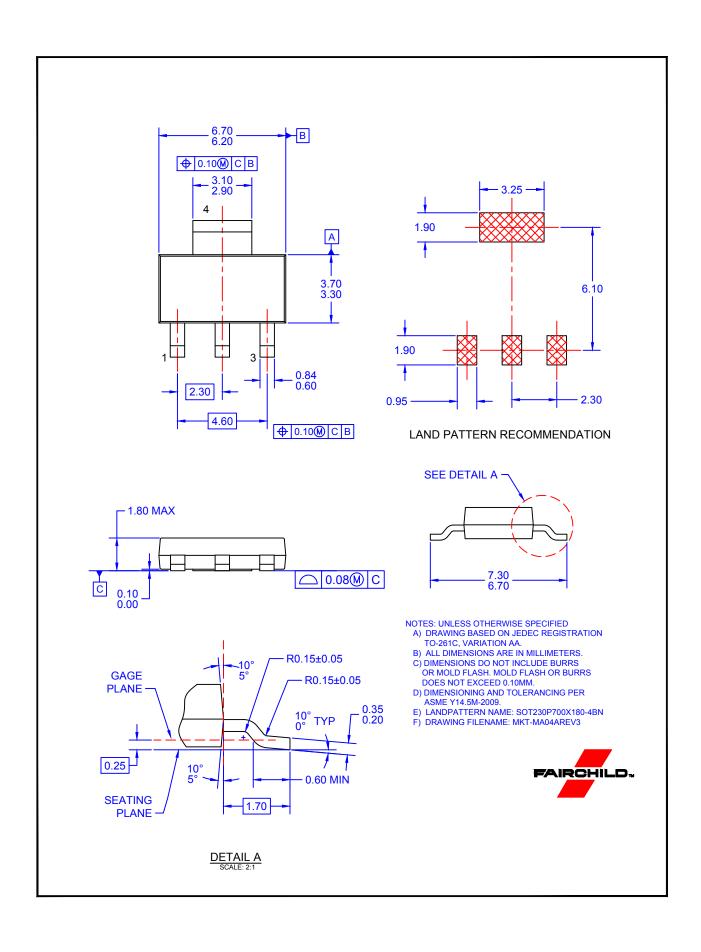


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.







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